

P-Channel 20 V (D-S) MOSFET

| PRODUCT SUMMARY | | | |
|---------------------|------------------------------------|------------------------------------|-----------------------|
| V _{DS} (V) | R _{DS(on)} (Ω) Max. | I _D (A) ^{a, d} | Q _g (Typ.) |
| -20 | 0.0080 at V _{GS} = -4.5 V | -16.7 | 70 nC |
| | 0.0086 at V _{GS} = -3.7 V | -16.1 | |
| | 0.0110 at V _{GS} = -2.5 V | -14.2 | |
| | 0.0185 at V _{GS} = -1.8 V | -11 | |

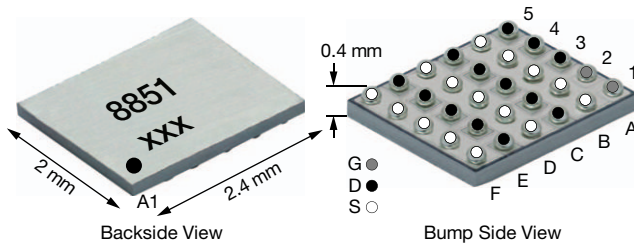
FEATURES

- TrenchFET[®] power MOSFET
- Small 2.4 mm x 2 mm outline area
- Low 0.4 mm max. profile
- Typical ESD protection 6000 V HBM
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



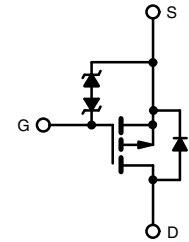
RoHS
COMPLIANT
HALOGEN
FREE

Power MICRO FOOT[®] 2.4 x 2



APPLICATIONS

- Battery switch / load switch
- Power management
- For smart phones, tablet PCs, and mobile computing



P-Channel MOSFET

Ordering Information:

Si8851EDB-T2-E1 (Lead (Pb)-free and halogen-free)

| ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted) | | | |
|---|-----------------------------------|------------------------|--------------------|
| PARAMETER | SYMBOL | LIMIT | UNIT |
| Drain-Source Voltage | V _{DS} | -20 | V |
| Gate-Source Voltage | V _{GS} | ± 8 | |
| Continuous Drain Current (T _J = 150 °C) | I _D | T _A = 25 °C | -16.7 ^a |
| | | T _A = 70 °C | -13.4 ^a |
| | | T _A = 25 °C | -7.7 ^b |
| | | T _A = 70 °C | -6.2 ^b |
| Pulsed Drain Current (t = 100 μs) | I _{DM} | -80 | A |
| Continuous Source-Drain Diode Current | I _S | T _C = 25 °C | |
| | | T _A = 25 °C | -0.55 ^b |
| Maximum Power Dissipation | P _D | T _A = 25 °C | 3.1 ^a |
| | | T _A = 70 °C | 2 ^a |
| | | T _A = 25 °C | 0.66 ^b |
| | | T _A = 70 °C | 0.43 ^b |
| Operating Junction and Storage Temperature Range | T _J , T _{stg} | -55 to +150 | °C |
| Package Reflow Conditions ^c | VPR | 260 | |
| | IR/Convection | 260 | |

Notes

- Surface mounted on 1" x 1" FR4 board with full copper, t = 5 s.
- Surface mounted on 1" x 1" FR4 board with minimum copper, t = 5 s.
- Refer to IPC/JEDEC[®] (J-STD-020), no manual or hand soldering.
- Based on T_A = 25 °C.

| THERMAL RESISTANCE RATINGS | | | | | |
|---|---------|-------------------|---------|---------|------|
| PARAMETER | | SYMBOL | Typical | Maximum | Unit |
| Maximum Junction-to-Ambient ^{a, b} | t = 5 s | R _{thJA} | 30 | 40 | °C/W |
| Maximum Junction-to-Ambient ^{c, d} | t = 5 s | | 145 | 188 | |

Notes

- Surface mounted on 1" x 1" FR4 board with full copper.
- Maximum under steady state conditions is 85 °C/W.
- Surface mounted on 1" x 1" FR4 board with minimum copper.
- Maximum under steady state conditions is 330 °C/W.



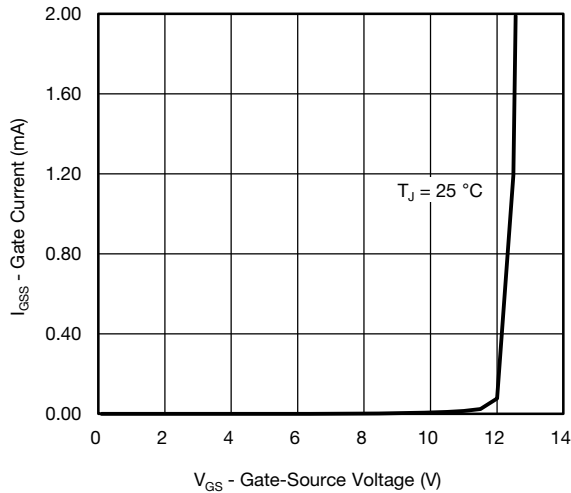
| SPECIFICATIONS (T _J = 25 °C, unless otherwise noted) | | | | | | | |
|---|--------------------------------------|---|-------------------------------------|--------|--------|-------|----|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT | |
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | V _{GS} = 0 V, I _D = -250 μA | -20 | - | - | V | |
| V _{DS} Temperature Coefficient | ΔV _{DS} /T _J | I _D = -250 μA | - | -11 | - | mV/°C | |
| V _{GS(th)} Temperature Coefficient | ΔV _{GS(th)} /T _J | | - | 3 | - | | |
| Gate-Source Threshold Voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D = -250 μA | -0.45 | - | -1 | V | |
| Gate-Source Leakage | I _{GSS} | V _{DS} = 0 V, V _{GS} = ± 4.5 V | - | - | ± 0.5 | μA | |
| | | V _{DS} = 0 V, V _{GS} = ± 8 V | - | - | ± 10 | | |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = -20 V, V _{GS} = 0 V | - | - | -1 | | |
| | | V _{DS} = -20 V, V _{GS} = 0 V, T _J = 70 °C | - | - | -10 | | |
| On-State Drain Current ^a | I _{D(on)} | V _{DS} ≤ -5 V, V _{GS} = -4.5 V | -5 | - | - | A | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = -4.5 V, I _D = -7 A | - | 0.0060 | 0.0080 | Ω | |
| | | V _{GS} = -3.7 V, I _D = -7 A | - | 0.0065 | 0.0086 | | |
| | | V _{GS} = -2.5 V, I _D = -5 A | - | 0.0081 | 0.0110 | | |
| | | V _{GS} = -1.8 V, I _D = -3 A | - | 0.0130 | 0.0185 | | |
| Forward Transconductance ^a | g _{fs} | V _{DS} = -10 V, I _D = -7 A | - | 50 | - | S | |
| Dynamic^b | | | | | | | |
| Input Capacitance | C _{iss} | V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz | - | 6900 | - | pF | |
| Output Capacitance | C _{oss} | | - | 640 | - | | |
| Reverse Transfer Capacitance | C _{rss} | | - | 715 | - | | |
| Total Gate Charge | Q _g | V _{DS} = -10 V, V _{GS} = -8 V, I _D = -5 A | - | 120 | 180 | nC | |
| | | | - | 70 | 105 | | |
| Gate-Source Charge | Q _{gs} | V _{DS} = -10 V, V _{GS} = -4.5 V, I _D = -5 A | - | 8 | - | | |
| Gate-Drain Charge | Q _{gd} | | - | 14 | - | | |
| Gate Resistance | R _g | | V _{GS} = -0.1 V, f = 1 MHz | - | 2.3 | | - |
| Turn-On Delay Time | t _{d(on)} | V _{DD} = -10 V, R _L = 2 Ω I _D ≅ -5 A, V _{GEN} = -4.5 V, R _g = 1 Ω | - | 35 | 70 | | ns |
| Rise Time | t _r | | - | 40 | 80 | | |
| Turn-Off Delay Time | t _{d(off)} | | - | 115 | 230 | | |
| Fall Time | t _f | | - | 35 | 70 | | |
| Turn-On Delay Time | t _{d(on)} | V _{DD} = -10 V, R _L = 2 Ω I _D ≅ -5 A, V _{GEN} = -8 V, R _g = 1 Ω | - | 15 | 30 | | |
| Rise Time | t _r | | - | 10 | 20 | | |
| Turn-Off Delay Time | t _{d(off)} | | - | 110 | 220 | | |
| Fall Time | t _f | | - | 25 | 50 | | |
| Drain-Source Body Diode Characteristics | | | | | | | |
| Continuous Source-Drain Diode Current | I _S | T _A = 25 °C | - | - | -2.6 | A | |
| Pulse Diode Forward Current (t = 100 μs) | I _{SM} | | - | - | -80 | | |
| Body Diode Voltage | V _{SD} | I _S = -5 A, V _{GS} = 0 V | - | -0.8 | -1.2 | V | |
| Body Diode Reverse Recovery Time | t _{rr} | I _F = -5 A, di/dt = 100 A/μs, T _J = 25 °C | - | 40 | 80 | ns | |
| Body Diode Reverse Recovery Charge | Q _{rr} | | - | 30 | 60 | nC | |
| Reverse Recovery Fall Time | t _a | | - | 16 | - | ns | |
| Reverse Recovery Rise Time | t _b | | - | 24 | - | | |

Notes

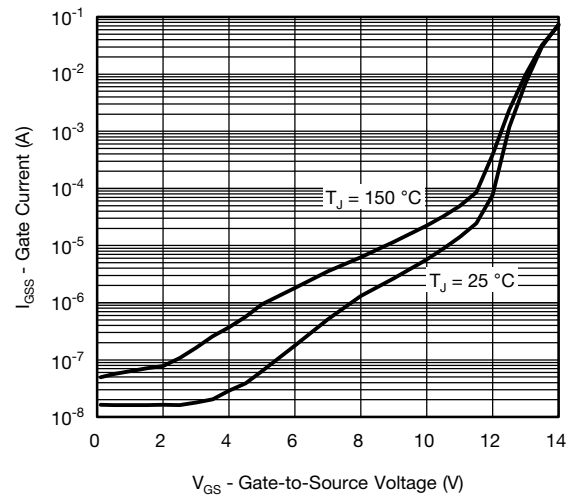
- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

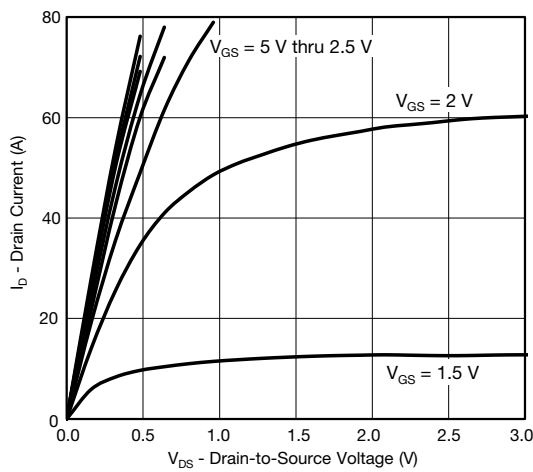
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



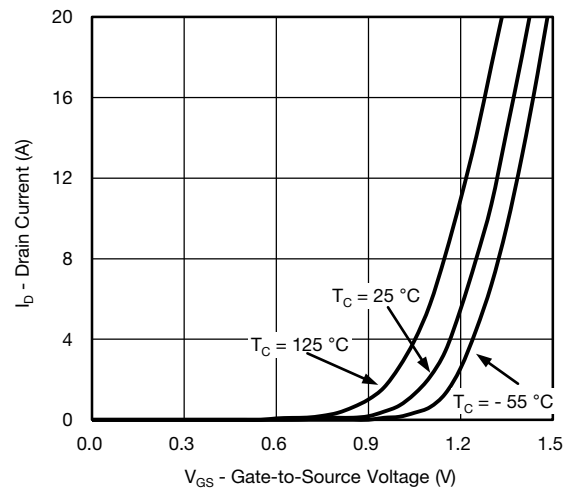
Gate Current vs. Gate-Source Voltage



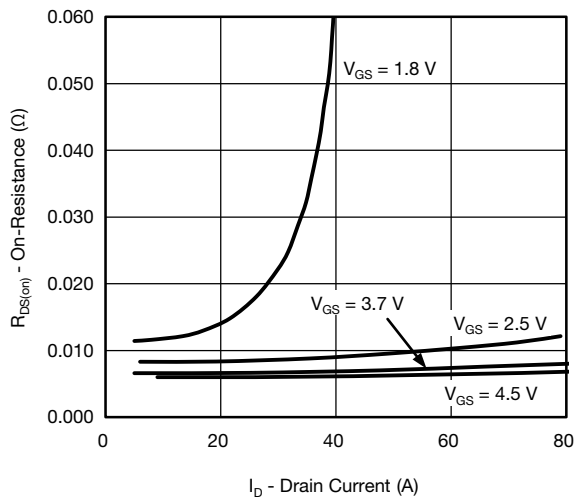
Gate Current vs. Gate-Source Voltage



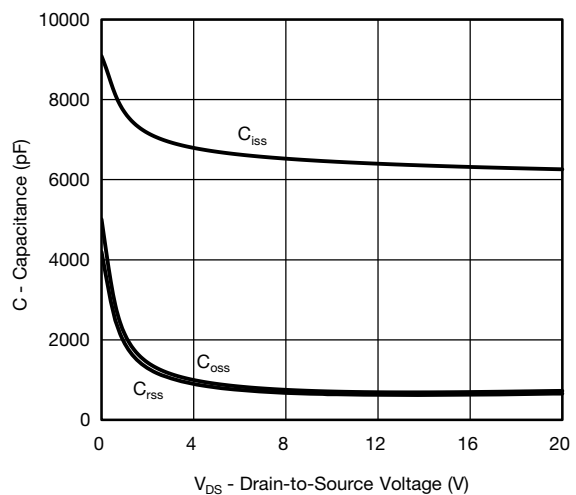
Output Characteristics



Transfer Characteristics



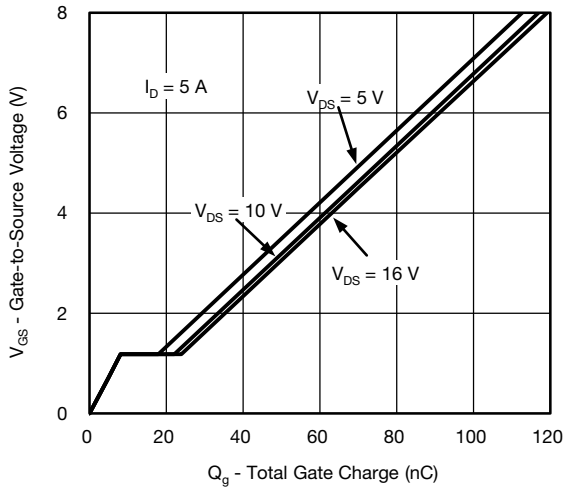
On-Resistance vs. Drain Current and Gate Voltage



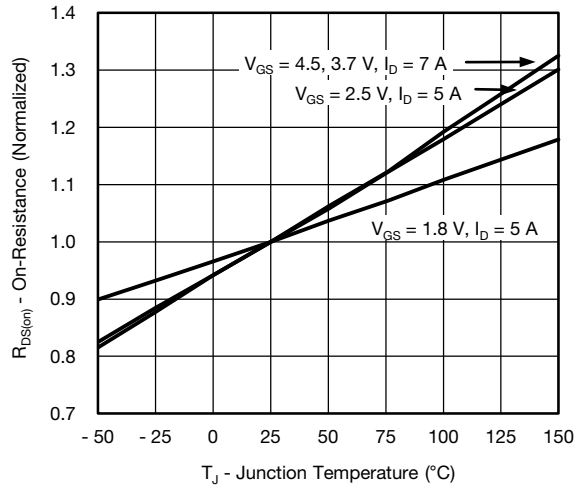
Capacitance



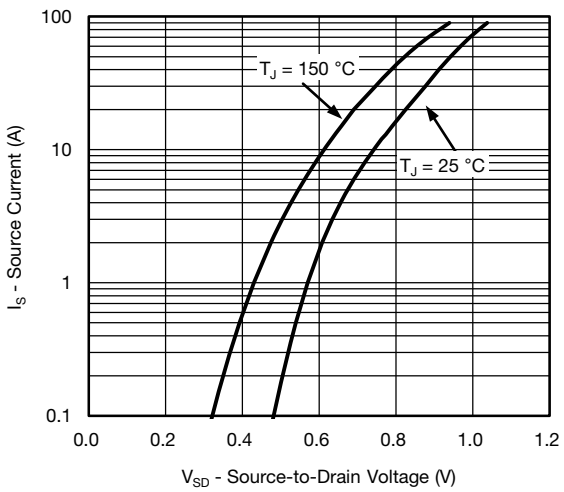
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



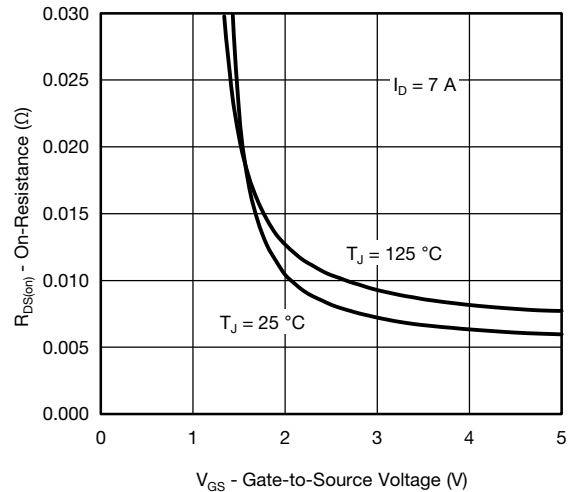
Gate Charge



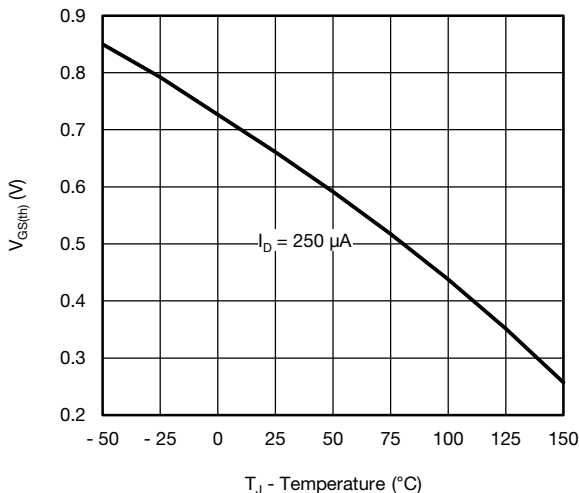
On-Resistance vs. Junction Temperature



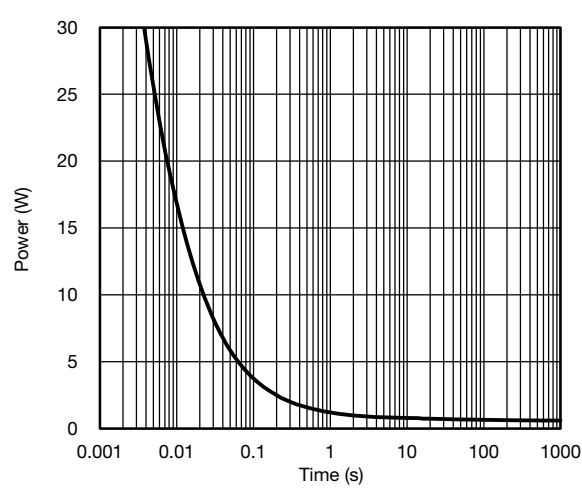
Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



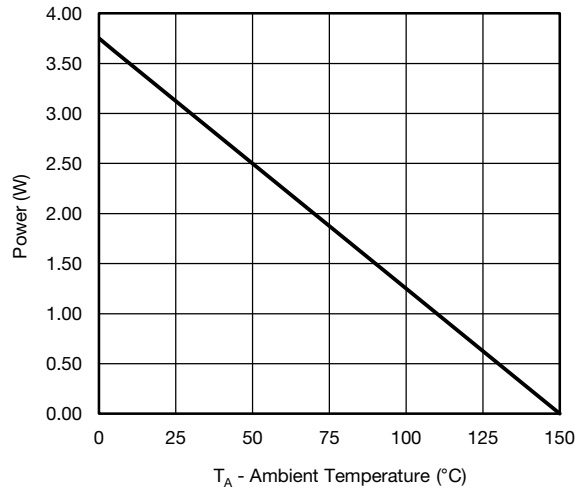
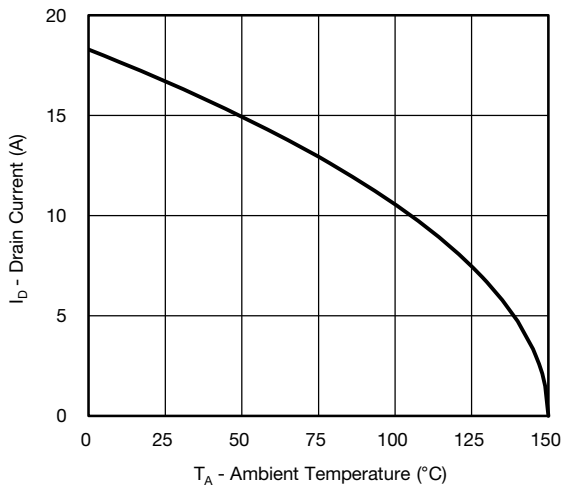
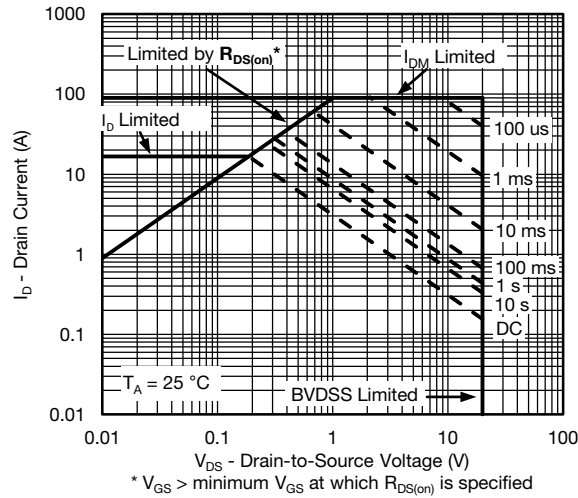
Threshold Voltage



Single Pulse Power, Junction-to-Ambient



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

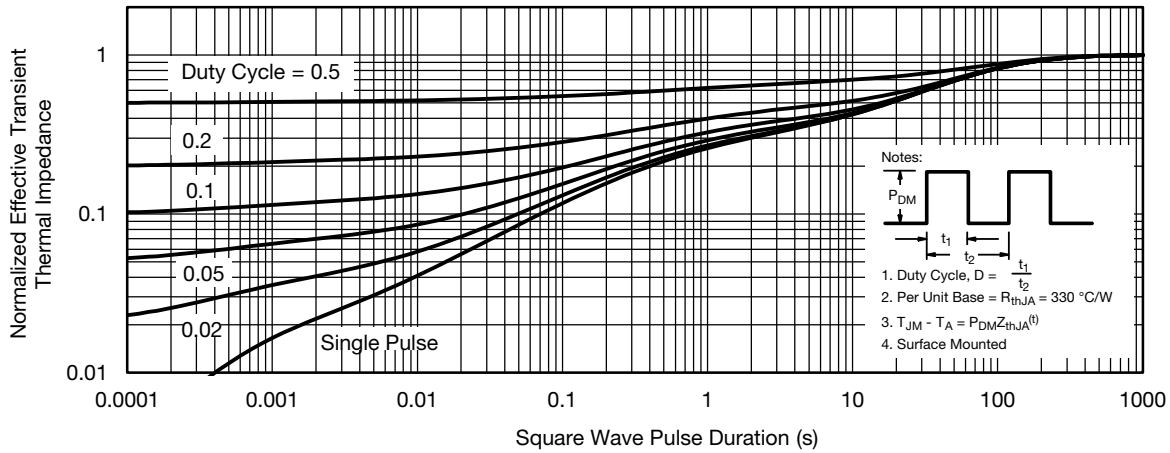


Note

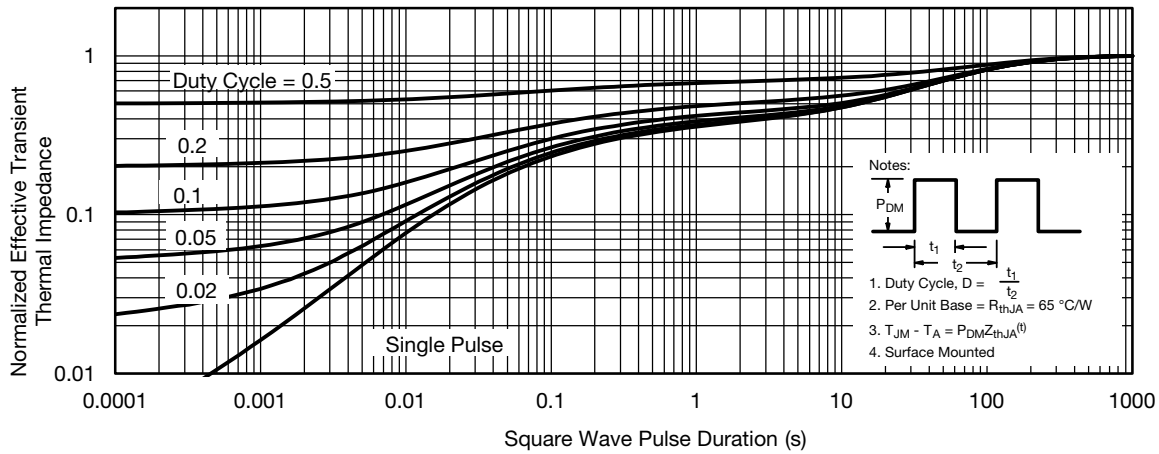
a. When mounted on 1" x 1" FR4 with full copper and $t = 5$ s



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



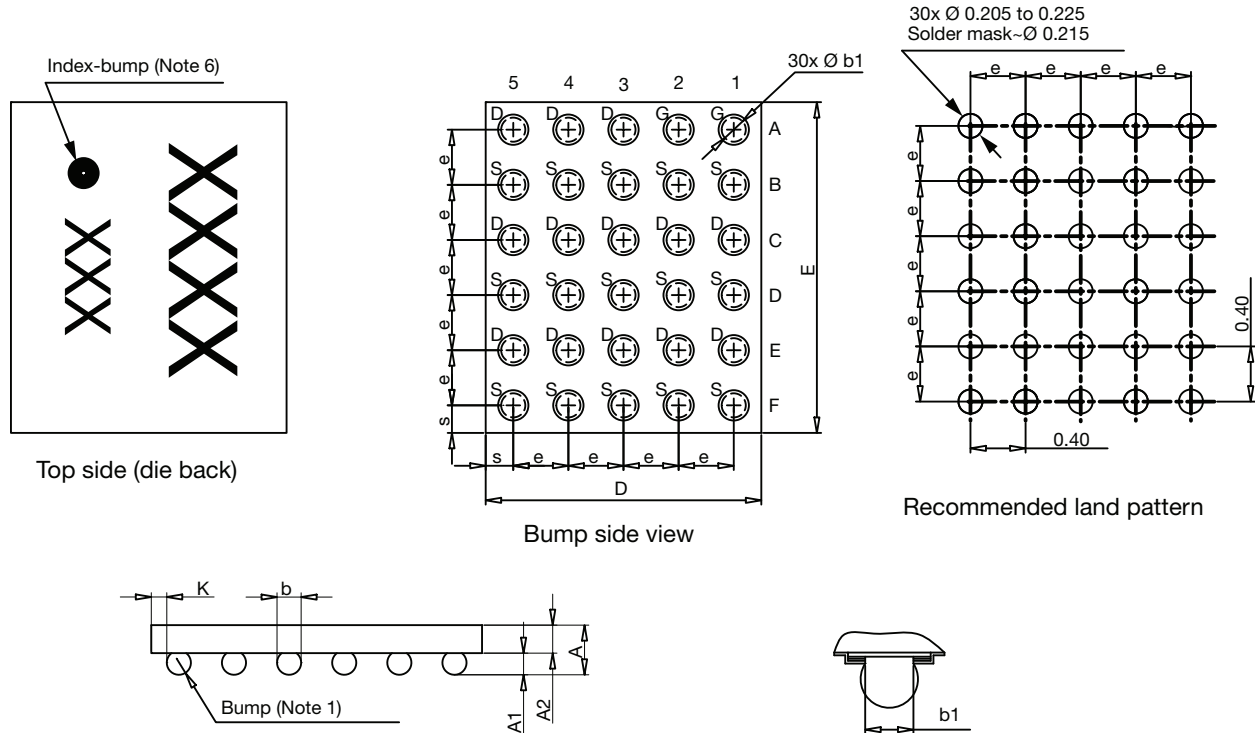
Normalized Thermal Transient Impedance, Junction-to-Ambient (on 1" x 1" FR4 Board with minimum Copper)



Normalized Thermal Transient Impedance, Junction-to-Ambient (on 1" x 1" FR4 Board with maximum Copper)

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MICRO FOOT[®]: 30-Bumps (2.4 mm x 2 mm, 0.4 mm Pitch, 0.184 mm Bump Height)


Notes

1. Bumps are 95.5/3.8/0.7 Sn/Ag/Cu.
2. Backside surface is coated with a Ti/Ni/Ag layer.
3. Non-solder mask defined copper landing pad.
4. Laser marks on the silicon die back.
5. "b1" is the diameter of the solderable substrate surface, defined by an opening in the solder resist layer solder mask defined.
6. • is the location of pin 1

| DIM. | MILLIMETERS | | | INCHES | | |
|------|-------------|-------|-------|--------|--------|--------|
| | MIN. | NOM. | MAX. | MIN. | NOM. | MAX. |
| A | 0.328 | 0.365 | 0.402 | 0.0129 | 0.0144 | 0.0158 |
| A1 | 0.136 | 0.160 | 0.184 | 0.0054 | 0.0063 | 0.0072 |
| A2 | 0.192 | 0.205 | 0.218 | 0.0076 | 0.0081 | 0.0086 |
| b | 0.200 | 0.220 | 0.240 | 0.0079 | 0.0087 | 0.0094 |
| b1 | | 0.175 | | | 0.0069 | |
| e | | 0.400 | | | 0.0157 | |
| s | 0.160 | 0.180 | 0.200 | 0.0063 | 0.0071 | 0.0079 |
| D | 1.920 | 1.960 | 2.000 | 0.0756 | 0.0772 | 0.0787 |
| E | 2.320 | 2.360 | 2.400 | 0.0913 | 0.0929 | 0.0945 |
| K | 0.040 | 0.070 | 0.100 | 0.0016 | 0.0028 | 0.0039 |

Note

- Use millimeters as the primary measurement.

ECN: T15-0177-Rev. A, 27-Apr-15
DWG: 6040



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